	9144030070855050X9		
			0755-33810388
	(Printed Circuit Board PCB) (High Density Interconnection HDI) (Flexible Printed Circuit FPC) / ISO9001 ISO14001 ISO14064 ISO45001 ISO50001 QC080000		

						39 ( ) 10 ( )		
				/	(mg/m^3)		mg/m^3	
					0.007	0.03	7	
					0.35	1.676	30	
					0.022	0.077	30	
					0.55	2.61	200	
					0.03	0.0071	0.5	
				VOCs	3.7	3.69	80	
					0	0	1.0	
					3.038	3.61	120	
					21.9	0.647	150	
					0.79	0.073	50	
					0	0	20	
					0	/		
					0	0	8.5	
					2.418	4.071	120	
				GB21900-2008 5 VOCs DB44/815-2010 2 DB44/765-2019 2 DB44/27-2001 2 DB44/ 2367-2022 1				

			( )	( )		[redacted]
			340.1	340.1		[redacted]
			5173.548	5173.548		[redacted]
			1560.373	1560.373		[redacted]

			0.55954	0.55954		
			1840.79	1840.79		
			915.43	915.43		5.
			1.08434	1.08434		
			0.38	0.38		
			32.84	32.84		6.
			164.2	164.2		
			146.64	148. 64		
			149.23	149.23		
			6.49	6.49		7.
			0.05	0.05		
			64.642	64.642		
			186.357	186.357		8.
		( )	16.123	16.123		
		FPC	4.854	4.854		

9.

PP

10.

			0.33	0.33		1. 2. 3. 4. 5. 6. ( )
			1.425	1.425		
			2147.58	2147 .58		
			0.02	0.02		
			5.51	5.51		
			18.34	18.34		
			0.41	0.41		
		(18-40L)	4.81	4.81		
			1.612	1.612		
			166.468	166.468		

		Leq	Leq	Leq	Leq	
	1 1#	61	53	65	55	
	1 2#	59	54			
	1 3#	58	53			
	1 4#	61	53			
	1 1#	59	54			
	1 2#	62	53			
	1 3#	61	53			
	1 4#	60	53			

			2006 12	12000 /	
			2006 12	153.5 /	
		( )	2018 6	26.6 /	
			2021 9	8000 /	
			2023 6	30000 /	

( )		2005-12-23	[2005]213			
( )		2006-08-10	[2006]102172			
( ) 2017		2009-09-08	[2009]100917		2007/7/19	[2007]075
					2009/2/9	[2009]021
					2011/4/11	[2011]026
		2018-04-28	2018 600129		2021/3/17	
					2022/8/4	
		2020-11-10	2020 000193		2022/5/21	

		2022-12-09	[2022]000033			

			2023-1-17 2022-9-14
	1 , 2 3 3.1		

Ï

	1. COD pH 2.2018 5 15 (2012) 3. 440 RMB
	2018 9 , (SZDB/Z 151-2015) 5

1.

2. 2016 41

2024 4 3